What is claimed is:

1. A laminate support used in the process of wire bonding a circuit device, comprising a closed woven mesh having strands whose separation distance is equal to or less than the diameter of said wire of said circuit device.

2. The laminate support used in the process of wire bonding a circuit device in accordance with claim 1, wherein said separation distance is no greater than 0.7 mils.

3. The laminate support used in the process of wire bonding a circuit device in accordance with claim 1, wherein said separation distance is between 0.2 and 0.7 mils.

4. The laminate support used in the process of wire bonding a circuit device in accordance with claim 1, wherein said laminate support comprises fiberglass.

5. The laminate support used in the process of wire bonding a circuit device in accordance with claim 1, wherein said laminate support is between approximately 2.5 and 4 mils thick.

6. The laminate support used in the process of wire bonding a circuit device in accordance with claim 1, wherein said circuit device is a pad of large scale integrated design.

7. A laminate support used in the process of wire bonding a circuit device, comprising a closed woven mesh having warp and weave strands, whose separation distance is equal to or less than the thickness of said wire of said circuit device, as measured lengthwise through said closed woven mesh.

8. The laminate support used in the process of wire bonding a circuit device in accordance with claim 7, wherein said separation distance is equal to or less than 0.7 mils.

9. The laminate support used in the process of wire bonding a circuit device in accordance with claim 7, wherein said separation distance is between 0.2 and 0.7 mils.

10. The laminate support used in the process of wire bonding a circuit device in accordance with claim 7, wherein said laminate support comprises fiberglass.

11. The laminate support used in the process of wire bonding a circuit device in accordance with claim 7, wherein said laminate support is between approximately 2.5 and 4 mils thick.

12. The laminate support used in the process of wire bonding a circuit device in accordance with claim 7, wherein said circuit device comprises a pad of large scale integrated design.

13. A laminate support used in the process of wire bonding a circuit device, comprising a closed woven mesh having warp and weave strands, whose separation distance is no greater than the diameter of said wire of said circuit device as measured lengthwise through said closed woven mesh, and wherein said separation distance is approximately equal to or less than 0.7 mils.

14. The laminate support used in the process of wire bonding a circuit device in accordance with claim 13, wherein said separation distance is between 0.2 and 0.7 mils.

15. The laminate support used in the process of wire bonding a circuit device in accordance with claim 13, wherein said laminate support comprises fiberglass.

16. The laminate support used in the process of wire bonding a circuit device in accordance with claim 13, wherein said laminate support is between approximately 2.5 and 4 mils thick.

17. The laminate support used in the process of wire bonding a circuit device in accordance with claim 13, wherein said circuit device comprises a pad of large scale integrated design.

18. A method for supporting a circuit device during wire bonding, comprising the steps of:

a) applying a capillary tool to wire that is to be bonded to a circuit device; and

b) supporting said circuit device upon a closed woven mesh whose separation distance between woven strands is less than or equal to a diameter of said wire.

19. The method of claim 18, wherein said separation distance is approximately equal to or less than 0.7 mils.

20. The method of claim 18, wherein said separation distance is between approximately 0.2 and 0.7 mils.